

Abstract of the Disclosure

A semiconductor device capable mounting semiconductor elements having different functions without increasing the area of the semiconductor device, and its manufacturing method are presented. A part of wiring 104 is formed also at the side surface of a semiconductor element 101, and bump electrodes 102 formed so as to be nearly on a same plane as the wiring 104 formed at the side surface of the semiconductor element 101, at least a part of ball electrodes 103 is formed so as to connect electrically to the wiring 104 at the side surface of the semiconductor element, the side surface of the semiconductor element is sealed with resin exposing the wiring 104, and the confronting surface of the circuit forming surface is sealed with resin.

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